

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

1. Canceled
2. Canceled
3. Canceled
4. (Currently amended) A device in accordance with claim 8 ~~1 or 2~~, in which said wiring is formed by using conductive paste.
5. (Currently amended) A device in accordance with ~~either of claim 8 1, 2 or 4~~, in which said wiring is formed by way of transfer printing.
6. (Currently amended) A device in accordance with claim 8 ~~1 or 2~~, in which said wiring is formed on the bottom surface of the substrate.
7. (Currently amended) A device in accordance with claim 8 ~~1 or 2~~, in which said connecting device is made of conductive material having a step corresponding to a profile of said acoustic wave transducer.
8. (Currently amended) An acoustic contact detecting A device comprising in accordance with claim 1 or 2, in which
 - (a) a substrate having a top surface and a bottom surface;
 - (b) an acoustic wave transducer for coupling with a first wave representative of a bulk wave being propagated between the top surface and the bottom surface through said substrate along an axis crossing said top surface, said acoustic wave transducer comprising ~~comprises~~ a piezoelectric substrate and a piezoelectric vibrator having electrode sections disposed on both surfaces of said piezo electric substrate, ~~and;~~
 - (c) a planar wiring for supplying said acoustic wave transducer with electric power, said planar wiring comprising ~~comprises~~ a first wiring section capable of contacting with one of said electrode sections of said piezoelectric vibrator by way of line or face contact and a second wiring section spaced and insulated from said first wiring section, ~~wherein;~~

(d) a connecting device for connecting said acoustic wave transducer with the planar wiring, said connecting device being is formed in a form capable of connecting the other electrode section of said piezoelectric vibrator with said second wiring section;

(e) a diffractive acoustic wave mode coupler having a mode of converted wave having high energy on said top surface and functioning for coupling a second wave being propagated along an axis parallel to said top surface with said first wave; and

(f) a means for detecting a perturbation in the energy of said second wave.

9. Canceled

10. Canceled

11. Canceled

13. Canceled

14. Canceled

15. (New) A device in accordance with claim 4, in which said wiring is formed by way of transfer printing.

16. (New) A coordinate input device of touch-type comprising:

a propagation medium having a top surface and a bottom surface, said top surface being capable of propagating an acoustic wave;

a bulk wave generation means for propagating a bulk wave in a crossing direction with respect to said top surface of said propagation medium, said bulk wave generation means comprising an acoustic wave transducer comprising a piezoelectric substrate and a piezoelectric vibrator having electrode sections disposed on both surfaces of said piezoelectric substrate;

a planar wiring for supplying this bulk wave generation means with electric power, said planar wiring comprising a first wiring section capable of contacting with one of said electrode sections of said piezoelectric vibrator by way of line or face contact and a second wiring section spaced and insulated from said first wiring section;

a connecting device for providing an electrical connection between said bulk wave generation means and said planar wiring, said connecting device being formed in a form capable of connecting the other electrode section of said piezoelectric vibrator with said second wiring section;

an acoustic wave generation means for converting said bulk wave into an acoustic wave and propagating said acoustic wave on the top surface of said propagation medium; and

a detecting means for detecting a scatter in the surface of the acoustic wave from said acoustic wave generation means.

17. (New) A device in accordance with claim 16, in which said wiring is formed by using conductive paste.

18. (New) A device in accordance with claim 16, in which said wiring is formed by way of transfer printing.

19. (New) A device in accordance with claim 16, in which said wiring is formed on the bottom surface of the substrate.

20. (New) A device in accordance with claim 16, in which said connecting device is made of conductive material having a step corresponding to a profile of said acoustic wave transducer.